

描述 / Descriptions

表面贴装整流二极管，反向电压：50~1000V，正向电流：5.0A，SMC 封装。
Surface Mount General Purpose Silicon Rectifier, Reverse Voltage: 50 to 1000 V, Forward Current: 5.0A, SMC package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟RoHS指令2011/65/EU，适用于表面贴装，无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications, Halogen free product.

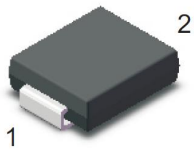
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

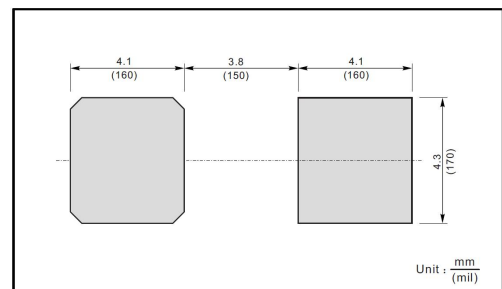


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S5AC	S5BC	S5DC	S5GC	S5JC	S5KC	S5MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0							A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	120							A
Typical Junction Capacitance ¹⁾	C_i	50							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	35							°C/W
	$R_{\theta JC}$	13							
Operating Junction Temperature Range	T_j	-55~+150							°C
Storage Temperature Range	T_{stg}	-55~+150							°C

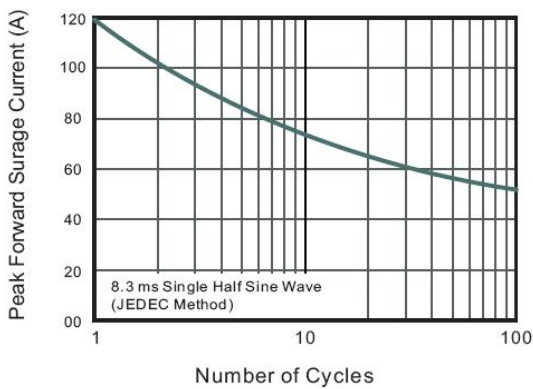
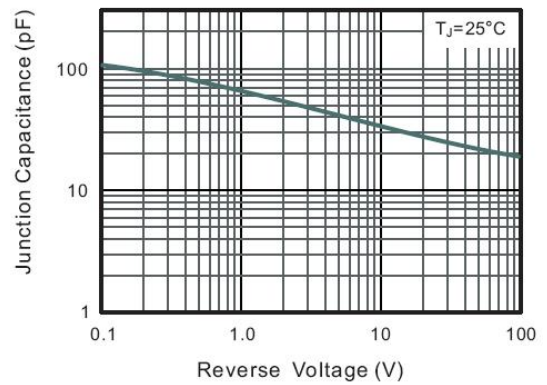
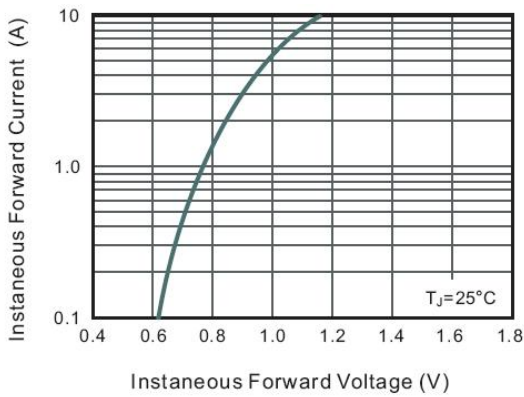
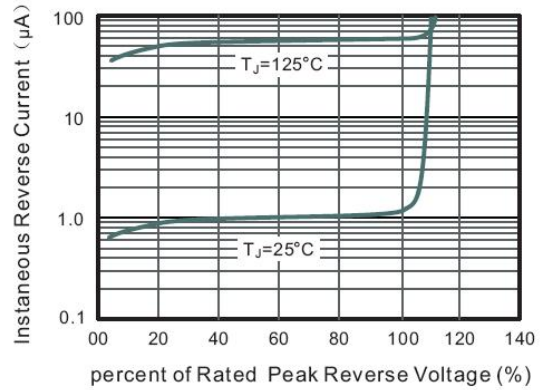
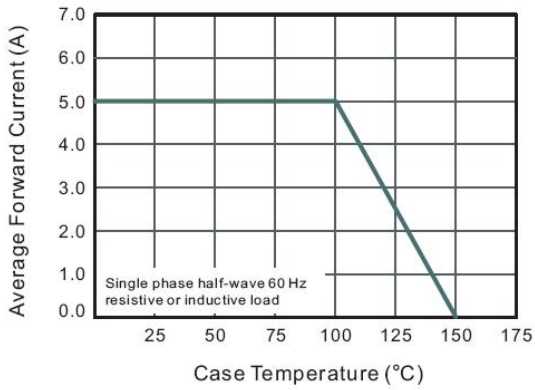
Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S5AC	S5BC	S5DC	S5GC	S5JC	S5KC	S5MC	
Max Instantaneous Forward Voltage	V_F	$I_F=5.0A$	1.0							V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I_R	$T_a=25^\circ C$	5							uA
		$T_a=100^\circ C$	100							

电参数曲线图 / Electrical Characteristic Curve



Marking

Type number	Marking code
S5AC	S5A
S5BC	S5B
S5DC	S5D
S5GC	S5G
S5JC	S5J
S5KC	S5K
S5MC	S5M

印章说明 / Marking Instructions



说明

S5A : 为型号代码

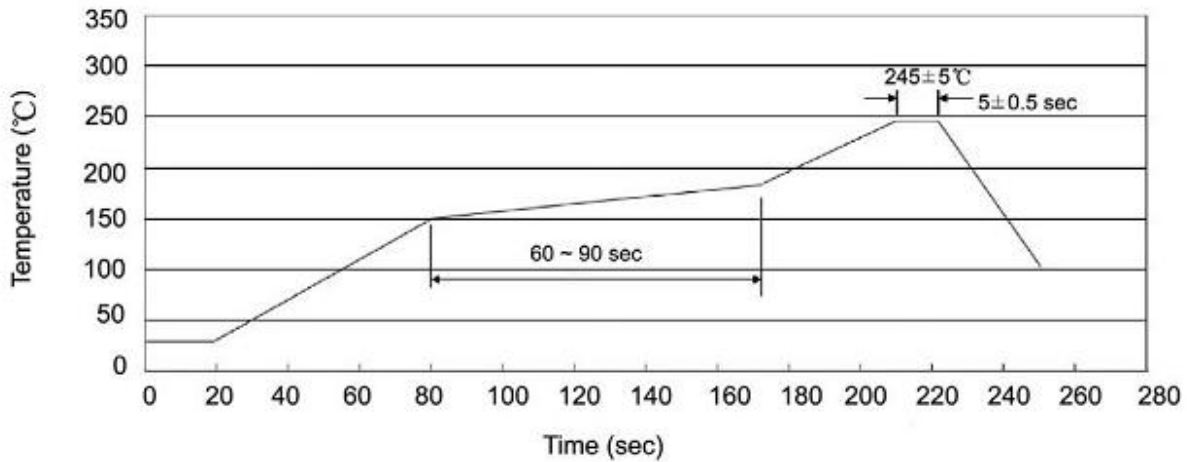
**** : 为生产批号追溯码, 第 1 个*为年月代码, 后面 3 个*为当月小批号代码

Note:

S5A : Product Type Code

**** : Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No
Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMC	3000	2	6000	6	36000	13" ×16	337X337X49	380X335X366

使用说明 / Notices